# **Aluminium-Substituted ZnO Thin Films: Thermoelectric Properties and Structural Characterisation**



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### Introduction and Motivation

### Zinc Oxide as a Thermoelectric Material

- High Seebeck coefficient S for bulk material (-300 to -400 μV/K [1])
- · Low production costs and non-toxicity
- High electrical resistivity  $\rho$  and thermal conductivity  $\kappa$  (10  $\Omega cm$  and 50 W/mK at RT [1])

# Substituting Zinc with Aluminium: $Zn_{0.98}AI_{0.02}O$

- · Lower electrical resistivity (ca  $0.005 \Omega$ cm from RT to  $1000^{\circ}$ C [1])
- · Thermal conductivity still a drawback

### **Reducing Thermal Conductivity**

- Lower dimensionality
- Morphology on nano-scale range and 2D thin films [2]

# **Synthesis**

#### Magnetron Sputtering [3]:

- · Radio-frequency (RF) method, plasma power 200 W
- Gas: mixture of Ar and Ar with 3% O<sub>2</sub>
- Target: 2 wt% Al<sub>2</sub>O<sub>3</sub>-doped ZnO
- Deposition pressure: 10-3 mbar
- Deposition time: 16 min
- · Substrate: Soda-lime glass
- Film thickness: 470 nm

# Morphology

### Columnar grains:

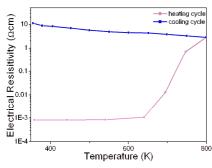


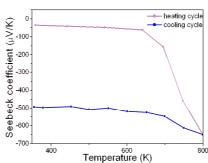


Fig. 2: TEM images of as grown  $Zn_{0.98}AI_{0.02}O$ films: a) BF, b) DF Film thickness th = 470 nmgrains ca 450 nm long and 15-35 nm wide The preferential orientation c-axis the perpendicular substrate.

# **Thermoelectric Properties**

Abrupt change in thermoelectric properties when heating in air above around 640 K:





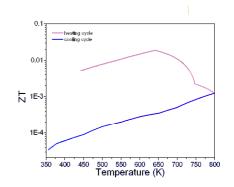
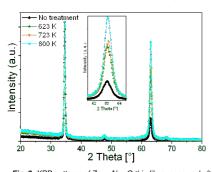
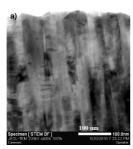


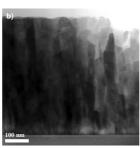
Fig. 6: Thermoelectric properties of a  $Zn_{0.98}Al_{0.02}O$  thin film. From left to right: 1) Electrical resistivity  $\rho(T)$ , 2: Seebeck coefficient S(T), 3: Estimated ZT values as a function of the temperature calculated from the  $\rho(T)$  and S(T)from the thin film and an approximation of the thermal conductivity of a bulk sample from solid state reaction.

# Morphology and Crystal Structure with Temperature Treatment

Possible change in orientation with temperature: Similar morphology before and after annealing treatment::







But more different orientations after than before annealing treatment:

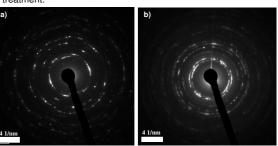


Fig. 3: XRD patterns of Zn<sub>0.98</sub>Al<sub>0.02</sub>O thin films measured after annealing treatment at different temperatures

**Fig. 4:** TEM images of  $Zn_{0.98}Al_{0.02}O$  thin films: a) before annealing treatment, b) after annealing treatment at 800 K.

Fig. 5: Electron diffraction of Zn<sub>0.98</sub>Al<sub>0.02</sub>O thin films: a) before annealing treatment, b) after annealing treatment at 800 K.

### **Conclusions**

- ⇒The films show columnar grains with preferred orientation of the c-axis perpendicular to the substrate.
- ⇒ There is an abrupt change in the thermoelectric properties around 640 K.
- ⇒ The change could be due to the anisotropic character of the ZnO sample with a hexagonal structure ( $\rho_{ab}$  +  $\rho_c$  [4]). The orientation of the grains change to more ab-plane contribution perpendicular to the substrate
- ⇒ However, as the difference in the electrical resistivity before and after annealing treatment is large, the more reasonable explanation is due to a change in the oxygen

### Outlook

⇒ More investigation on the grain orientation and the change in oxygen content with temperature will be done by TEM and by X-ray photoelectron spectroscopy (XPS).

# Acknowledgement



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- [1] Tsubota T. et al. *J. Mater. Chem.* 7(1) (1997) 85 [2] Dresselhaus M.S. et al. *Adv. Mater.* 19 (2007) 1043
- [3] Haug F.-J. et al. *J. Vac. Sci. Technol. A* 19 (2001) 171 [4] Kaga H. et al. *Ceramics International* 34 (2008) 1097